



Transformer

EE Series



Product Specification

Product type	Specifications	Application	Dimension (mm)
EE10	1.20kHz-300KHz 2.0.5W-5.0W 3. -25°C to +105°C 4.Insulation Class:B(130°C)	1.Power converter transformers and chokes, 2. Driver transformer Pulse transformer Chokes, Inductors, and filters for communication equipment, etc	
EE13	1.20kHz-500KH 2.0.5W-10W 3. -25°C to +105°C 4.Insulation Class:B(130°C)	1.Power converter transformers and chokes, 2. Driver transformer Pulse transformer Chokes, Inductors, and filters for communication equipment, etc	
EE16	1.20kHz-500KH 2.0.5W-15W 3. -25°C to +105°C 4.Insulation Class:B(130°C)	1.Power converter transformers and chokes, 2. Driver transformer Pulse transformer Chokes, Inductors, and filters for communication equipment, etc	
EE19	1.20kHz-500KH 2.0.5W-18W 3. -25°C to +105°C 4.Insulation Class:B(130°C)	1.Power converter transformers and chokes, 2. Driver transformer Pulse transformer Chokes, Inductors, and filters for communication equipment, etc	

※ Special inquires besides the above common used types can be met on your requirement, Please contact your local sales.

The data is reference only. Customers should verify actual device performance in their specific applications. Specifications are subject to change without notice.Please check our website for latest information. <http://www.ftind.com>



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Electrial performance test

Item	Specification	Test Methods
Inductance	Refer to standard electrical spec.	HP4291B
DCR		Agilent 34401A

Reliability Performance test

Item	Specification	Test Methods
Vibration	Appearance: No damage L change: within±10% RDC: within specification Hi-POT: within specification	Test device shall be soldered on the substrate Oscillation Frequency: 10 to 55 to 10Hz for 1 min. Amplitude: 0.75 mm Time: 2 hrs for each axis (X, Y &Z), total 6 hrs
Solderability	90% covered with solder	Pre-heating: 150°C, 1min Solder Composition: Sn/Ag/Cu=95.6/3.0/0.5 Solder Temperature: 245±5°C Immersion Time: 4±1sec
Resistance to Soldering Heat	Appearance: No Damage	Pre-heating:150°C,1Min. Solder Composition: Sn/Ag/Cu=95.6/3.0/0.5 Solder Temperature: 260±5°C Immersion Time: 4±1Sec.

Environmental test

Temperature Shock	Appearance: No damage L change: within±10% RDC: within specification Hi-POT: within specification	10 cycles (Air to Air) 1 cycles shall consist of: 30 minutes exposure to -55 °C 30 minutes exposure to 125 °C 15 seconds maximum transition between high and low temperatures
Temperature Cycle	Appearance: No damage L change: within specification RDC: within specification Hi-POT: within specification	One cycle: One cycle/step1: -25±3°C for 30min step2: 25±2°C for 3min step3:105±3°C for 30min step4:25±2°C for 3min Total: 10 cycles Measured after exposure in the room condition for 24hrs
Humidity Test	Appearance: No damage L change: within specification RDC: within specification Hi-POT: within specification	Temperature: 60±2°C Relative Humidity: 90 ~ 95% Time: 96±5hrs Measured after exposure in the room condition for 24hrs
High Temperature Storage		Temperature: 125±2°C Time: 96±5hrs Measured after exposure in the room condition for 24hrs
Low Temperature Storage		Temperature: -40±2°C Time: 96±5hrs Measured after exposure in the room condition for 24hrs

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